10-02-1998

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ASSI … **ER SHEET** *Patents Only*

To the Honorable Commissioner of Pat

September 22, 1998
Attorney Dkt: 5649-603

Please record the attached original documents or copy thereof.

1998 SEP 25 AM 3: 28
OPR/FINANCE

1. Name of conveying party(ies): Dae-Won Ha 9-25-98 Additional name(s) of conveying party(ies) attached? ___ Yes _X_ No	2. Name and address of receiving party(ies): Samsung Electronics Co., Ltd. 416 Maetan-dong, Paldal-gu Suwon-City, Kyungki-do Republic of Korea Additional name(s) & address(es) attached? ___ Yes _X_ No
3. Nature of conveyance: _X_ Assignment ___ Merger ___ Security Agreement ___ Change of Name ___ Other ______________ Execution Date: August 22, 1998	

4. Application Serial No. 09/143,131, filed August 28, 1998 Patent No. ______________

If this document is being filed together with a new application, the execution date of the application is: ______________

Additional numbers attached? ___ Yes _X_ No

5. Name and address of party to whom correspondence concerning document should be mailed: **Mitchell S. Bigel** **Myers Bigel Sibley & Sajovec** **P.O. Box 37428** **Raleigh, North Carolina 27627**	6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) $ 40.00 _X_ Enclosed ___ Authorized to be charged to deposit account 8. Deposit account number: **50-0220** (Attach duplicate copy of this page if paying by deposit account)

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09/29/1998 DNGUYEN 00000144 09143131
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9. Statement and signature
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mitchell S. Bigel, #29,614 — Mitchell Bigel — September 22, 1998
Signature Date

Total number of pages including cover sheet, attachments and document: 3

ASSIGNMENT

THIS ASSIGNMENT, made by me, Dae-Won Ha, citizen of the Republic of Korea, residing at 510-357, Jukong Apt., Jamsil-dong, Songpa-ku, Seoul, Republic of Korea

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **METHODS OF FABRICATING INTEGRATED CIRCUIT FIELD EFFECT TRANSISTORS BY PERFORMING MULTIPLE IMPLANTS PRIOR TO FORMING THE GATE INSULATING LAYER THEREOF**, for which an application for United States Letters Patent has been filed in the United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 09/143,131, filed August 28, 1998) the filing date and application number of said application when known, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to bind my heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 22 day of August, 1998.

Daewon Ha (SEAL)
Dae-Won Ha

Witnessed by:

KyuHyun Lee

Date: 22/8/1998

Hongsik Jeong

Date: 22/8/1998